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(71)Applicant : AKISHIMA KAGAKU KOGYO KK

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(72)Inventor : TSUKUDA SHUICHI
FUJITA TOMOAKI

(54) THERMOPLASTIC RESIN COMPOSITION

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a thermoplastic resin composition largely improved in plate-out on the surface of a treating machine during heat molding by extrusion molding, injection molding, calendering, powder molding, etc., and bad effects on printing and heat sealing by suppressing blooming and bleeding of compounding agents on the surface of the product after molding, and improved in the properties of printing, adhesion, and heat sealing.

SOLUTION: This thermoplastic resin composition is prepared by compounding at least one compound (A) selected from the group consisting of polyoxyalkylene alkyl ether phosphoric acid ester and/or polyoxyalkylene alkylallyl ether phosphoric acid ester and at least one compound (B) selected from the group consisting of polyoxyalkylene alkyl ether and polyoxyalkylene alkylallyl ether to 100 pts.wt. thermoplastic resin.

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